

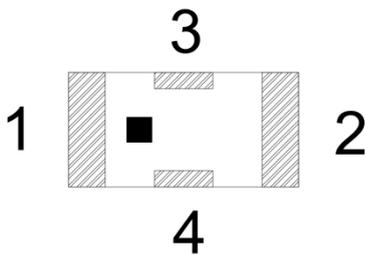
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

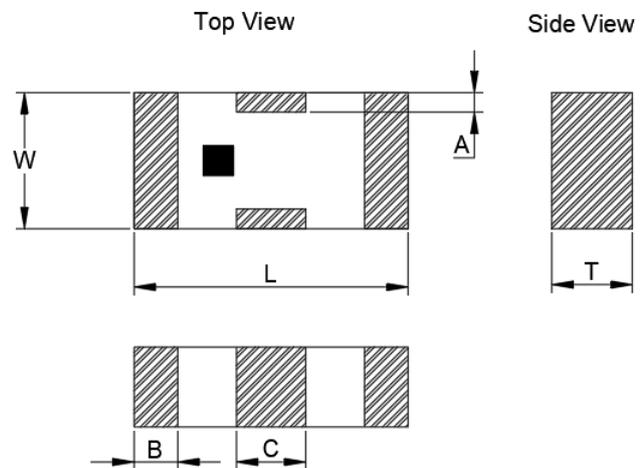
| NO. | Parameter | Frequency (MHz) | SPC | |
|-----|----------------------------------|-----------------|-------|------|
| | | | Min. | Max. |
| 1 | Insertion Loss (dB) | DC~530 | | 1.0 |
| 2 | VSWR | DC~530 | | 1.5 |
| 3 | Attenuation | 870~945 | 20 dB | |
| | | 945~3000 | 40 dB | |
| 4 | In/Output Impedance (Ω) | | 50 | |

Construction



| PIN | Connection |
|-----|-------------|
| 1 | Input Port |
| 2 | Output Port |
| 3 | GND |
| 4 | GND |

Dimensions



| Symbol | Dimension (mm) | Symbol | Dimension (mm) |
|--------|----------------|--------|----------------|
| L | 3.20±0.20 | A | 0.23±0.10 |
| W | 1.60±0.20 | B | 0.51±0.10 |
| T | 0.94±0.10 | C | 0.81±0.10 |

Typical Electrical Characteristics (T=25°C)

